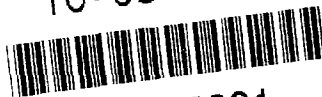



10-08-2004



To the Director, U.S. Patent and Trademark Office

Documents or copy thereof.

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<p>1. Name of conveying party(ies): (List using letter numbers for multiple parties)</p> <p>1. Akira SHIMIZU    2. Hideaki FUKUDA 3. Hiroki ARAI      4. Baiei KAWANO 5. Takayuki YAMAGISHI</p> <p>Additional name(s) of conveying party(ies) attached? ( ) Yes (X) No</p>	<p>2. Name and address of receiving party(ies):</p> <p><b>Name:</b> ASM JAPAN K.K. <b>Address:</b> 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan</p> <p>Additional name(s) of receiving party(ies) attached? ( ) Yes (X) No</p>
<p>3. Nature of conveyance:</p> <p>(X) Assignment      ( ) Security Agreement ( ) Merger          ( ) Change of Name ( ) Other:</p> <p>Execution Date: (List as in section 1 if multiple signatures) 1-4 executed on 8/10/04 and 5. executed on 8/9/04</p>	<p>4. Application number(s) or Patent number(s):</p> <p>(X) Patent Application No.: 10/897,061 Filing Date: July 22, 2004</p> <p>Additional numbers attached? ( ) Yes (X) No</p>
<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p><b>Name:</b> Katsuhiro Arai KNOBBE MARTENS OLSON &amp; BEAR LLP 2040 Main Street Fourteenth Floor Irvine, CA 92614 <b>Customer No.</b> 20,995 <b>Return Fax:</b> (949) 760-9502 <b>Attorney's Docket No.:</b> ASMJP.150AUS</p>	<p>6. Total number of applications and patents involved: 1</p> <p>7. Total fee (37 CFR 1.21(h)): \$40.00 (X) Enclosed</p> <p>8. Deposit account number: 11-1410 Please charge this account for any additional fees which may be required, or credit any overpayment to this account.</p>
<p>9. Statement and signature.</p> <p>To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document.</p> <p><u>Katsuhiro Arai</u> Name of Person Signing</p> <p><u></u> Signature</p> <p>October 1, 2004 Date</p> <p>43,315 Registration No.</p> <p>Total number of pages including cover sheet, attachments and document: 2</p>	

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40.00 OP

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Alexandria, VA 22313-1450

ASSIGNMENT

WHEREAS, I, Akira SHIMIZU, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, Hideaki FUKUDA, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, Hiroki ARAI, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, Baiei KAWANO, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, and Takayuki YAMAGISHI, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, have invented certain new and useful improvements in a SEMICONDUCTOR-PROCESSING APPARATUS PROVIDED WITH SUSCEPTOR AND PLACING BLOCK for which we have executed an application for Letters Patent in the United States, on July 22, 2004 as Application Serial No. 10/897,061;

AND WHEREAS, ASM JAPAN K. K. (hereinafter "ASSIGNEE"), a Japan Corporation, with its principal place of business at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventor, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

This 10 day of August, 2004

A. Shimizu  
Akira SHIMIZU

This 10 day of August, 2004

H. Fukuda  
Hideaki FUKUDA

This 10 day of August, 2004

H. Arai  
Hiroki ARAI

This 10 day of August, 2004

B. Kawano  
Baiei KAWANO

This 9 day of August, 2004

Takayuki Yamagishi  
Takayuki YAMAGISHI

A. Shimizu  
Witness